

CMOS Multifunction Expandable 8-Input Gate

High-Voltage Types (20-Volt Rating)

CD4048B is an 8-input gate having four control inputs. Three binary control inputs — K_a , K_b , and K_c — provide the implementation of eight different logic functions. These functions are OR, NOR, AND, NAND, OR/AND, OR/NAND, AND/OR and AND/NOR.

A fourth control input, K_d , provides the user with a 3-state output. When control input K_d is high, the output is either a logic 1 or a logic 0 depending on the inner states. When control input K_d is low, the output is an open circuit. This feature enables the user to connect this device to a common bus line.

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})

Voltages referenced to V_{SS} Terminal -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS

-0.5V to V_{DD} +0.5V

DC INPUT CURRENT, ANY ONE INPUT

±10mA

POWER DISSIPATION PER PACKAGE (P_D):

For $T_A = -55^\circ\text{C}$ to $+100^\circ\text{C}$ 500mW

For $T_A = +100^\circ\text{C}$ to $+125^\circ\text{C}$ Derate Linearity at 12mW/ $^\circ\text{C}$ to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$ 100mW

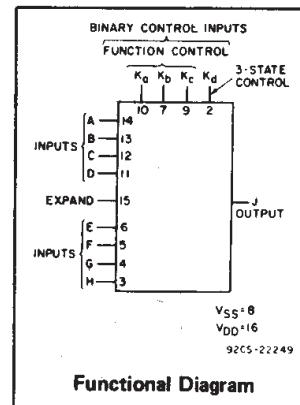
OPERATING-TEMPERATURE RANGE (T_A) -55 $^\circ\text{C}$ to +125 $^\circ\text{C}$

STORAGE TEMPERATURE RANGE ($T_{Storage}$) -65 $^\circ\text{C}$ to +150 $^\circ\text{C}$

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 \pm 1/32 inch (1.59 \pm 0.79mm) from case for 10s max +265 $^\circ\text{C}$

In addition to the eight input lines, an EXPAND input is provided that permits the user to increase the number of inputs into a CD4048B (see Fig. 2). For example, two CD4048B's can be cascaded to provide a 16-input multifunction gate. When the EXPAND input is not used, it should be connected to V_{SS} . The CD4048B-series types are supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic packages (E suffix), and in chip form (H suffix).



Features:

- Three-state output
- Many logic functions available in one package
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V (full package-temperature range), 100 nA at 18 V and 25 $^\circ\text{C}$
- Noise margin (full package-temperature range) = 1 V at $V_{DD}=5$ V, 2 V at $V_{DD}=10$ V, 2.5 V at $V_{DD}=15$ V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

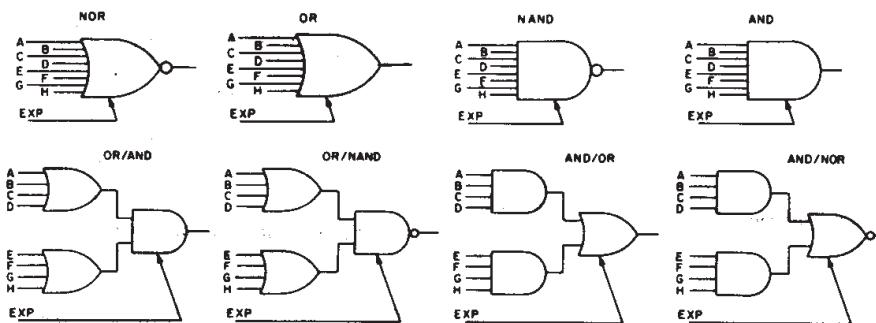
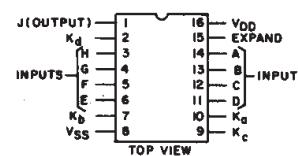


Fig. 1 – Basic logic configurations.

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For $T_A = \text{Full Package Temperature Range}$)	3	18	V



TERMINAL ASSIGNMENT

CD4048B Types

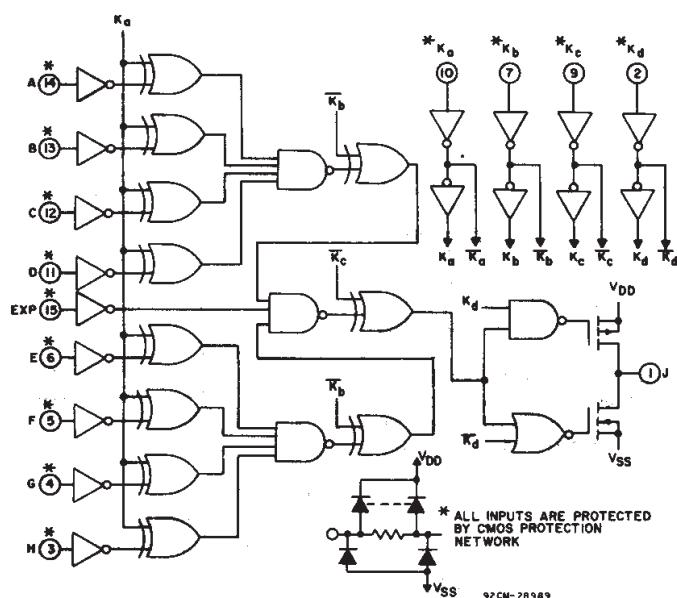


Fig. 2 – Logic diagram.

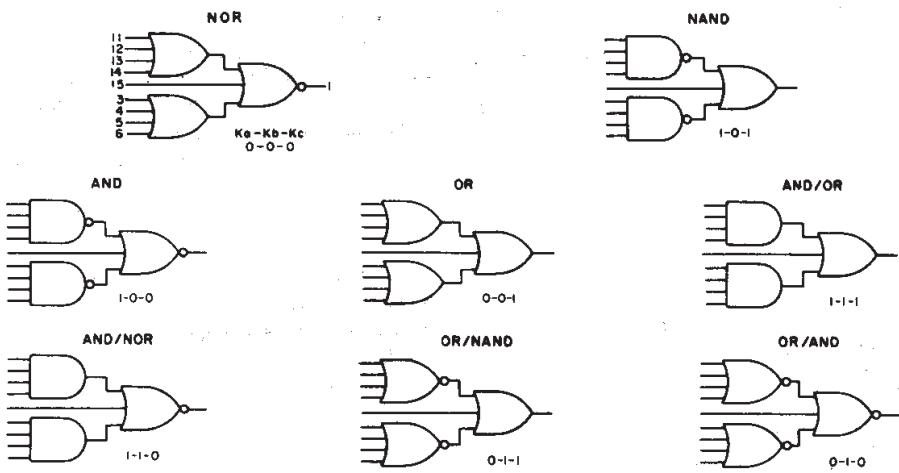


Fig. 3 – Actual-circuit logic configurations.

APPLICATIONS OF EXPAND INPUT

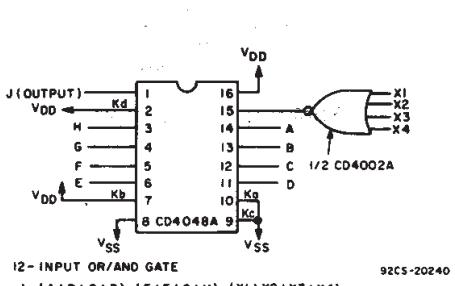


Fig. 4 – 12-input OR/AND gate.

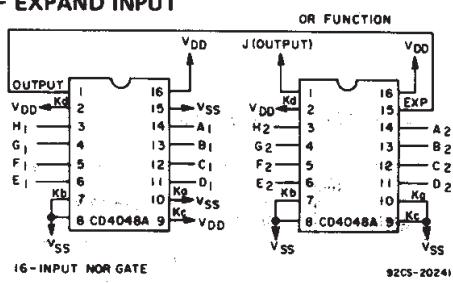


Fig. 5 – 16-input NOR gate.

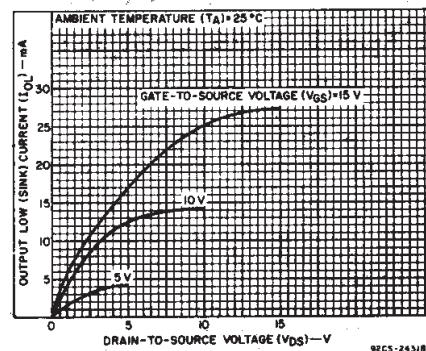


Fig. 6 – Typical output low (sink) current characteristics.

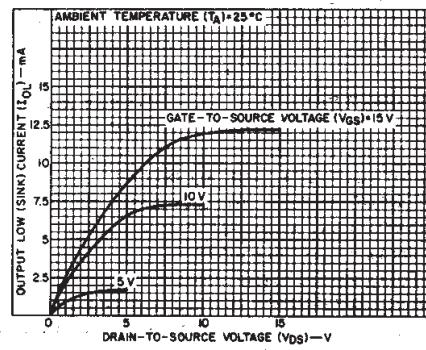


Fig. 7 – Minimum output low (sink) current characteristics.

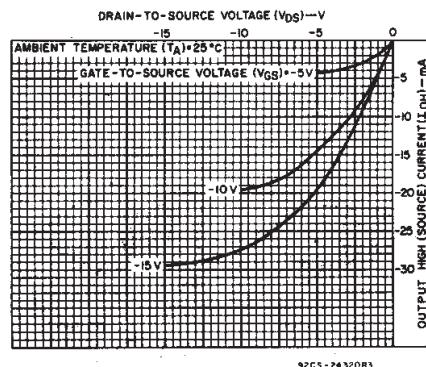


Fig. 8 – Typical output high (source) current characteristics.

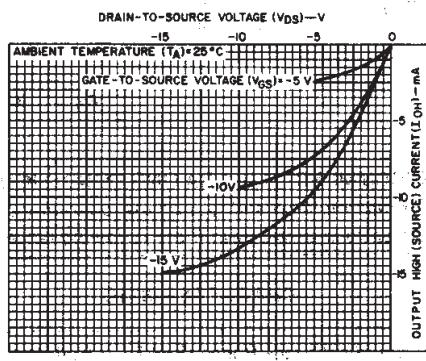


Fig. 9 – Minimum output high (source) current characteristics.

CD4048B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)						UNITS	
				-55		-40	+85	+125	+25		
	V _O (V)	V _{IN} (V)	V _{DD} (V)						Min.	Typ.	Max.
Quiescent Device Current, I _{DD} Max.	—	0,5	5	0,25	0,25	7,5	7,5	—	0,01	0,25	μA
	—	0,10	10	0,5	0,5	15	15	—	0,01	0,5	
	—	0,15	15	1	1	30	30	—	0,01	1	
	—	0,20	20	5	5	150	150	—	0,02	5	
Output Low (Sink) Current I _{OL} Min.	0,4	0,5	5	0,64	0,61	0,42	0,36	0,51	1	—	mA
	0,5	0,10	10	1,6	1,5	1,1	0,9	1,3	2,6	—	
	1,5	0,15	15	4,2	4	2,8	2,4	3,4	6,8	—	
Output High (Source) Current, I _{OH} Min.	4,6	0,5	5	-0,64	-0,61	-0,42	-0,36	-0,51	-1	—	mA
	2,5	0,5	5	-2	-1,8	-1,3	-1,15	-1,6	-3,2	—	
	9,5	0,10	10	-1,6	-1,5	-1,1	-0,9	-1,3	-2,6	—	
	13,5	0,15	15	-4,2	-4	-2,8	-2,4	-3,4	-6,8	—	
Output Voltage: Low-Level, VOL Max.	—	0,5	5	0,05			—	0	0,05	—	V
	—	0,10	10	0,05			—	0	0,05	—	
	—	0,15	15	0,05			—	0	0,05	—	
Output Voltage: High-Level, VOH Min.	—	0,5	5	4,95			4,95	5	—	—	V
	—	0,10	10	9,95			9,95	10	—	—	
	—	0,15	15	14,95			14,95	15	—	—	
Input Low Voltage, V _{IL} Max.	0,5,4,5	—	5	1,5			—	—	1,5	—	V
	1,9	—	10	3			—	—	3	—	
	1,5,13,5	—	15	4			—	—	4	—	
Input High Voltage, V _{JH} Min.	0,5,4,5	—	5	3,5			3,5	—	—	—	V
	1,9	—	10	7			7	—	—	—	
	1,5,13,5	—	15	11			11	—	—	—	
Input Current I _{IN} Max.	—	0,18	18	±0,1	±0,1	±1	±1	—	±10 ⁻⁵	±0,1	μA
3-State Output Current, I _{OUT}	0,18	0,18	18	±0,4	±0,4	±12	±12	—	±10 ⁻⁴	±0,4	μA

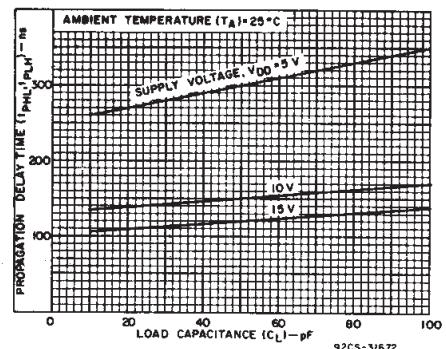


Fig. 10 – Typical propagation delay time (logic inputs to output) as a function of load capacitance.

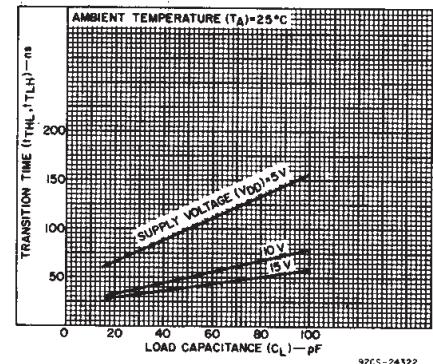


Fig. 11 – Typical transition time vs. load capacitance.

IMPLEMENTATION OF EXPAND INPUT FOR 9 OR MORE INPUTS

OUTPUT FUNCTION	FUNCTION NEEDED AT EXPAND INPUT	OUTPUT BOOLEAN EXPRESSION
NOR	OR	$J = \overline{(A+B+C+D+E+F+G+H)} + (\text{EXP})$
OR	OR	$J = (A+B+C+D+E+F+G+H) + (\text{EXP})$
AND	NAND	$J = \overline{(ABCDEFHG)} \cdot \overline{(\text{EXP})}$
NAND	NAND	$J = \overline{\overline{(ABCDEFHG)}} \cdot \overline{(\text{EXP})}$
OR/AND	NOR	$J = \overline{(A+B+C+D)} \cdot \overline{(E+F+G+H)} \cdot \overline{(\text{EXP})}$
OR/NAND	NOR	$J = \overline{(A+B+C+D)} \cdot \overline{(E+F+G+H)} \cdot \overline{(\text{EXP})}$
AND/NOR	AND	$J = \overline{(ABCD)} + \overline{(EFGH)} + (\text{EXP})$
AND/OR	AND	$J = \overline{(ABCD)} + \overline{(EFGH)} + (\text{EXP})$

Note: (EXP) designates the EXPAND function (i.e., $X_1+X_2+\dots+X_N$).

NOTE:
Refer to FUNCTION TRUTH TABLE for connection of unused inputs.

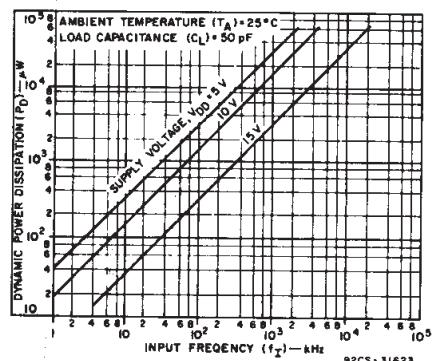


Fig. 12 – Typical power dissipation as a function of input frequency.

CD4048B Types

DYNAMIC CHARACTERISTICS at $T_A=25^\circ\text{C}$, $C_L=50 \mu\text{F}$, Input $t_r, t_f=20 \text{ ns}$,
 $R_L=200 \text{ k}\Omega$ unless otherwise specified

CHARACTERISTIC	TEST CONDITIONS	LIMITS		UNITS
		V _{DD} V	All Package Types Typ. Max.	
Propagation Delay: t_{PHL}, t_{PLH} Inputs to Output and K _a to Output	5 10 15	500	600	ns
		150	300	
		120	240	
	K _b to Output	225	450	
		85	170	
		55	110	
	K _c to Output	140	280	
		50	100	
		40	80	
	Expand Input to Output	190	380	
		90	180	
		65	130	
3-State Propagation Delay: K _d to Output t_{PHZ}, t_{PLZ} t_{PZH}, t_{PZL}	$R_L=1 \text{ k}\Omega$ See Fig. 21	5	80	ns
		10	35	
		15	25	
Transition Time: t_{THL}, t_{TLH}	5 10 15	100	200	pF
		50	100	
		40	80	
Input Capacitance: C_I	Any Input	5	7	
3-State Output Capacitance		5	10	

FUNCTION TRUTH TABLE

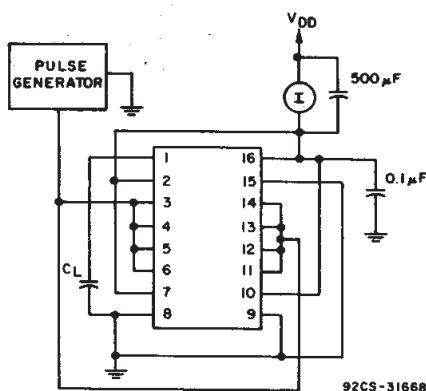


Fig. 13 – Dynamic power dissipation test circuit.

OUTPUT FUNCTION	BOOLEAN EXPRESSION	K _a	K _b	K _c	UNUSED INPUT*
NOR	$J=A+B+C+D+E+F+G+H$	0	0	0	V _{SS}
OR	$J=A+B+C+D+E+F+G+H$	0	0	1	V _{SS}
OR/AND	$J=(A+B+C+D) \cdot (E+F+G+H)$	0	1	0	V _{SS}
OR/NAND	$J=(A+B+C+D) \cdot (\overline{E+F+G+H})$	0	1	1	V _{SS}
AND	$J=ABCDEF GH$	1	0	0	V _{DD}
NAND	$J=\overline{ABCDEF GH}$	1	0	1	V _{DD}
AND/NOR	$J=\overline{ABCD} + EFGH$	1	1	0	V _{DD}
AND/OR	$J=ABCD + EFGH$	1	1	1	V _{DD}
$K_d=1$ Normal Inverter Action					
$K_d=0$ High Impedance Output					

K_d=1 Normal Inverter Action

K_d=0 High Impedance Output

EXPAND Input=0

* See Figs. 1,2,3,4, and 5.

TEST CIRCUITS - STATIC MEASUREMENTS

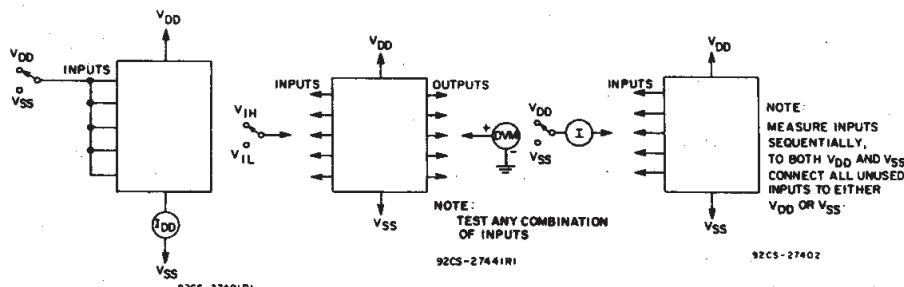


Fig. 14 – Quiescent device current test circuit.

Fig. 15 – Input voltage test circuit.

Fig. 16 – Input current test circuit.

CD4048B Types

TEST CIRCUITS - DYNAMIC MEASUREMENTS

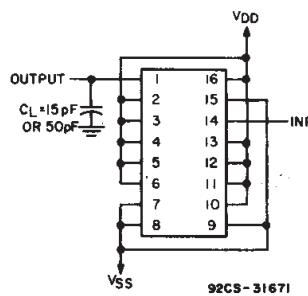


Fig. 17 – Test circuit for t_{PHL} , t_{THL} , and t_{TLH} (AND) measurements.

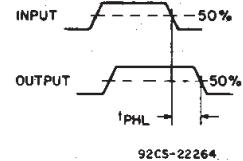


Fig. 18 – Waveforms for t_{PHL} and t_{PHL} (AND).

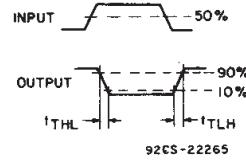


Fig. 19 – Waveforms for t_{THL} and t_{TLH} (AND).

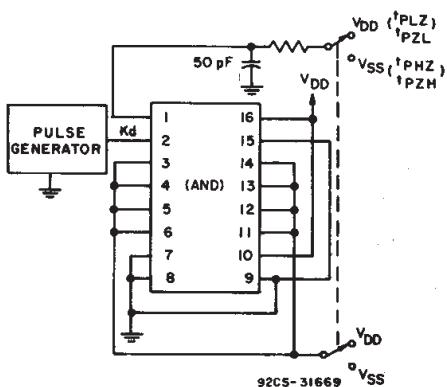


Fig. 20 – Test circuit for t_{PZL} , t_{PZH} , t_{PLZ} , and t_{PHZ} (AND).

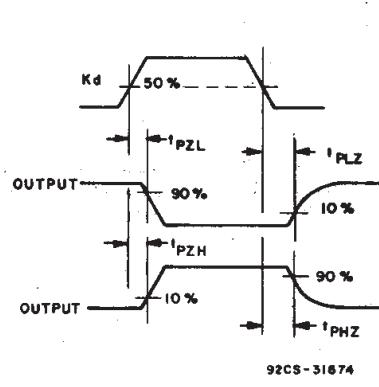
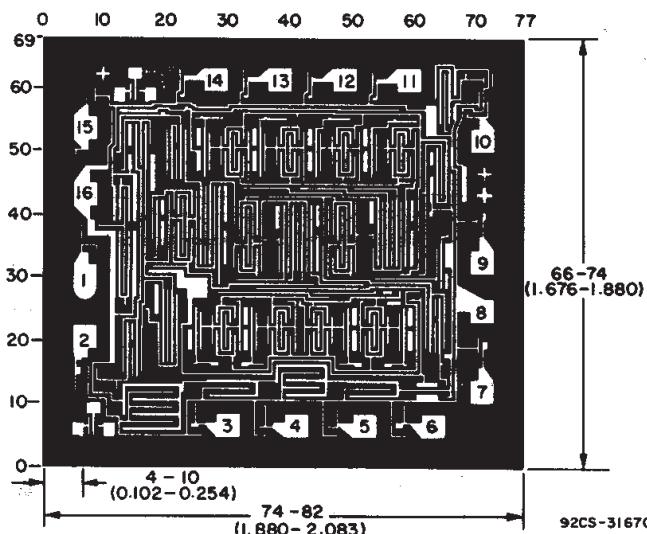


Fig. 21 – Waveforms for t_{PZL} , t_{PZH} , t_{PLZ} , and t_{PHZ} (AND).



Dimensions and pad layout for CD4048BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

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